FILM-LIKE ADHESIVE, ADHESIVE SHEET, AND SEMICONDUCTOR DEVICE USING SAME

ABSTRACT

This invention provides a film adhesive that can simultaneously satisfy process characteristics and reflow resistance requirements. The film adhesive is used for bonding a semiconductor element to an adherend and comprises an adhesive layer containing at least one resin selected from polyurethane imide resins, polyurethane amide imide resins, and polyurethane imide-polyurethane amide imide resins.

Fig. 1